

**IN THE SPECIFICATION**

Please replace the paragraphs beginning at Page 5, Line 8 of the Specification with the following amended paragraphs:

FIGURE 4 is a block diagram depicting protective cage on a MEMS device with the sacrificial layer removed; and

FIGURE 5 is a block diagram depicting protective layer deposited on the protective cage[.]; and

FIGURE 6 depicts additional material on the wafer.

Please replace the paragraph beginning at Page 11, Line 13 of the Specification with the following amended paragraph:

In step 113, additional material 560 may be deposited onto the wafer, as depicted in Figure 6. Typically, the additional material 560 is to increase the hermeticity of the packaged microcavity. However, step 113 may be necessary depending on the desired application. The additional material 560 can be the same or similar material to structural layer and depends on desired electrical properties. For example, for an RF MEMS application, the additional material 560 can be Silicon Dioxide ( $\text{SiO}_2$ ) or Silicon Nitride ( $\text{Si}_3\text{N}_4$ ).